WARNING

Only the CMi Staff is qualified to do a **service** or to do **maintenance**

If the target configuration doesn't fit with the one given on the user interface, please contact the staff.

**User manual**

1. **Login**
   1.1. Logon on the ACCESS CONTROL SYSTEM on the zone computer to unlock the Automatic function of the SPIDER 600
   1.2. Tab "Service" : Logon on the SPIDER 600

   - Click on "log on" and then enter "User" and "Password"
1.3. Tab "Online visualisation"

- Click on "Spider 600"
- Idle Status: Chambers = grey; Pumps & valves = green; Robot arm = magenta

2. Loading

2.1. Tab "Manual Operation"

- Click on "Load Lock" and "vent"
2.2. Open the load lock

![Image of the load lock]

2.3. Remove the cassette from the load lock

![Image of the cassette removal]
2.4. Put the cassette on the table and load wafers

2.4.1. Cassette:
- 2 bars on top, 1 bar on bottom
- Slot #25: Upper slot (first wafer which will be processed)
- Slot #01: Lower slot (last wafer which will be processed)

2.4.2. Wafer:
- Against white stop bars
- Flat parallel to the bar
- Side to be processed: UP

2.4.3. Stack of 2 wafers
- **ATTENTION:** Load one slot over two: Slots #25, #23, #21, etc...

2.4.4. Cleaning of the targets
- Load dummy wafers in the first slot positions for the target cleaning.
2.5. Put the cassette in the load lock and close the door

- Make sure that the white stop bars are on the load lock door side.

- Make sure that the lower bar is properly placed between black stoppers.
3. Recipe Selection and Start Production

3.1. Tab "Programs and recipes"

- Open the selected program with + and check the steps (Process Module number, recipe)

- Open a Process Module folder with + and
- Open a recipe (right click) and select properties

- Modify parameters (for example: Process time)
3.2. High temperature deposition

3.2.1. Check each recipe of each step to make sure that it's the same temperature

3.2.2. The ramp up procedure is included in the first recipe (for example: Therm-90mn-4) of the target cleaning program (for example: Al_T clean target PM4).

- Select "Heating" / "Setpoint curve" = "Ramp ..." (for example: "Ramp 300" for a ramp up from room T° to 300°C).

- Before processing any live wafer at high temperature, a target cleaning on a dummy wafer is mandatory because temperature ramp up and stabilization are done in this program!

3.3. Tab "Automatic"

- Click on "Discs"
- Select a program for each wafer in the cassette

3.3.2. Status color:

- White = Not processed
- Iridescent = Not processed, selected for the next production
- Yellow = In production
- Green = Processed
3.4. Start production for all wafers

- For "Plant", click on: "Automatic"

- If the button "Automatic" is dimmed, it means that you aren't logged on the ACCESS CONTROL SYSTEM on the zone computer

Online visualization / Spider 600 "In production"
3.5. End of process

- Idle Status : Chambers = grey ; Pumps & valves = green ; Robot arm = magenta
4. **Unloading**

4.1. Tab "Manual Operation"
   - Click on "Load Lock" and "vent"

4.2. Open the load lock

4.3. Remove the cassette from the load lock

4.4. Get back your substrate from the cassette

4.5. Replace the cassette in the load lock

4.6. Close the door of the load lock

4.7. Tab "Manual Operation"
   - Click on "Load Lock" and "high vacuum"

5. **Logout**

5.1. Tab "Service" : Logout from the SPIDER 600
   - Click on "log off"

5.2. Logout from the ACCESS CONTROL SYSTEM.